



Attorney Docket No. 9180-5

In re: J. Daniel Mis et al;

Serial No.: 09/966,316

Filed: September 27, 2001

PATENT

Group Art Unit 2811

Examiner: Nitin Parekh

Confirmation No.: 5045

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For: **METHODS OF FORMING METALLURGY STRUCTURES FOR WIRE AND
SOLDER BONDING AND RELATING STRUCTURES**

Date: December 4, 2002

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action dated November 6, 2002, the Applicants respectfully request entry of this amendment, and substantive examination on the merits. In particular, the Applicants elect prosecution of Claims 1-28, and 62-68 on the merits, cancellation of Claims 29-61, entry of new Claims 69-71, and amendment of the title to provided consistency with the elected claim set. Attached hereto is a marked up version of the changes made by the current amendment. The marked up version of the changes is captioned "**Version With Markings To Show Changes Made**".

In The Title:

Please enter the amendment of the title at all occurrences thereof to recite:

**"METHODS OF FORMING METALLURGY STRUCTURES FOR WIRE AND
SOLDER BONDING"**

In The Claims:

Please enter the cancellation of Claims 29-61.

Please enter new claims 69-76.

69.(New) A method of forming an electronic device comprising:
forming an input/output pad on a substrate;
forming a bonding structure on the input/output pad, the bonding structure including a barrier layer comprising nickel on the input/output pad, and a solder structure on the barrier layer.

70.(New) A method according to Claim 69 further comprising:
forming an under bump metallurgy layer between the nickel barrier layer and the input/output pad.

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Election

Amend A

FJONES

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